

Title (en)  
OPTOELECTRONIC DEVICE WITH A HOUSING BODY

Title (de)  
OPTOELEKTRONISCHE VORRICHTUNG MIT GEHÄUSEKÖRPER

Title (fr)  
DISPOSITIF OPTOÉLECTRONIQUE À CORPS DE LOGEMENT

Publication  
**EP 2126989 A1 20091202 (DE)**

Application  
**EP 08734323 A 20080226**

Priority  

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- DE 102007021904 A 20070510

Abstract (en)  
[origin: DE102007021904A1] The housing body (100) has a main surface (2) with a surface area (21,29) and another surface area (22). The former surface area and the latter surface area forms a layer in the main surface and both the surface areas are adjoined together by an outer edge (20). The latter surface area and the outer edge seal the former surface area. The former surface area forms a level. The housing body has a material made of a group and the group is formed by silicon, epoxy and silicon epoxy hybrid material. Independent claims are also included for the following: (1) an opto-electronic device has a housing body (2) a method for manufacturing an opto-electronic device.

IPC 8 full level  
**H01L 33/48** (2010.01); **H01L 33/54** (2010.01); **H01L 33/58** (2010.01)

CPC (source: CN EP US)  
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**H01L 2224/48091** (2013.01 - CN EP US); **H01L 2224/48247** (2013.01 - CN EP US); **H01L 2924/1815** (2013.01 - CN EP US)

Citation (search report)  
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**DE 102007021904 A1 20080904**; CN 101622724 A 20100106; CN 105140373 A 20151209; CN 105140373 B 20180918;  
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